

L Number	Hits	Search Text	DB	Time stamp
-	56	semiconductor adj substrate and inductor and capacitor and radio adj frequency and etching and monitoring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:36
-	130	(438/8).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:26
-	114	(438/13).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:28
-	259	radio adj frequency adj detection or radio adj frequency adj detector	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:30
-	17251	chemical adj etching	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 17:48
-	1	(radio adj frequency adj detection or radio adj frequency adj detector) and (chemical adj etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:33
-	141	lateral adj undercut	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:36
-	15708	resonate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:36
-	110	(chemical adj etching) and resonate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:36
-	1133640	semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:36
-	41	((chemical adj etching) and resonate) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:40
-	130	quartz adj crystal adj monitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:45
-	165128	receiver and transmitter	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:46
-	185	(chemical adj etching) and (receiver and transmitter)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 16:46

	2	5629244.URPN.	USPAT	2002/05/17 17:06
	22	5639423.URPN.	USPAT	2002/05/17 17:10
	30	("4219335" "4596697" "4598049" "4632808" "4673657" "4676274" "4683195" "4708931" "4737464" "4759828" "4908112" "4920056" "4952266" "4960486" "4963498" "5000817" "5003822" "5006749" "5129262" "5212988" "5220189" "5229297" "5252294" "5270183" "5296375" "5304487" "5385709" "5427946" "5486335" "5498392").PN.	USPAT	2002/05/17 17:12
	5	5282921.URPN.	USPAT	2002/05/17 17:16
	5	("2912497" "2967907" "3806643" "4423137" "4509162").PN.	USPAT	2002/05/17 17:17
	256	(438/381).CCLS.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/17 17:24
	48	rf adj etch	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/17 17:41
	5	5817573.URPN.	USPAT	2002/05/17 17:38
	5	5817573.URPN.	USPAT	2002/05/17 17:38
	14	("5141897" "5167760" "5231051" "5233223" "5254498" "5312773" "5326427" "5358621" "5364817" "5374849" "5387550" "5397742" "5407861" "5496773").PN.	USPAT	2002/05/17 17:38
	1	"non-contact detection system" and (etch or etching)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/17 17:43
	435	high adj frequency adj detection or high adj frequency adj detector	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/17 17:44
	330600	etch or etching	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/17 17:45
	653629	silicon	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/17 17:45
	6	(high adj frequency adj detection or high adj frequency adj detector) and (etch or etching) and silicon	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/17 17:45
	0	chemical adj etching and (high adj frequency adj detection or high adj frequency adj detector)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/17 17:48
	1	"secondary ion emission spectroscopy"	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 11:03

	1	"thickness detection" same radio	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 11:58
	4	"thickness detection" same rf	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 11:58
	14	"insitu" and etching and (rf or radio) and (monitoring or detection)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 12:03
	6	("4115184" "4207137" "4354154" "4963819" "5175472" "5273610") . PN.	USPAT	2002/05/19 12:08
	29	5467013.URPN.	USPAT	2002/05/19 12:09
	144	"lateral undercut" or "lateral under-cut"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 12:33
	5	(("6063642") or ("5559058")) . PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 12:45
	0	("physical adj measured and undercut") . PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 12:45
	0	("physical adj measured same undercut") . PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 12:46
	0	("physical adj measured same "undercut") . PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 12:46
	0	("undercut") . PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 12:46
	43622	undercut	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 13:33
	1134671	measured	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 12:47
	4169	undercut and measured	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 12:47
	653629	silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 12:47

	1209	(undercut and measured) and silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 12:47
	596606	lateral	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 12:48
	422	((undercut and measured) and silicon) and lateral	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 12:48
	1969	insitu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 12:48
	1	((undercut and measured) and silicon) and lateral) and insitu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 13:32
	3	("4763183" "5114233" "5539766").PN.	USPAT	2002/05/19 13:03
	5	5739909.URPN.	USPAT	2002/05/19 13:04
	252	(324/329).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 13:32
	57	(324/341).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 13:32
	264	(324/338).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 13:32
	9	(324/364).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 13:33
	301	(324/71.5).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 13:33
	609	undercut and ((324/329).CCLS.) or ((324/341).CCLS.) or ((324/338).CCLS.) or ((324/364).CCLS.) or ((324/71.5).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 13:34
	88	silicon and (undercut and ((324/329).CCLS.) or ((324/341).CCLS.) or ((324/338).CCLS.) or ((324/364).CCLS.) or ((324/71.5).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/19 13:34
	2	5027064.URPN.	USPAT	2002/05/19 13:42
	1926	sra or "surface resistance analyzer"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/20 15:22

	43622	undercut	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:22
	1133640	semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:23
	0	(sra or "surface resistance analyzer") and undercut and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:23
	276	(sra or "surface resistance analyzer") and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:23
	128630	etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:23
	4	((sra or "surface resistance analyzer") and semiconductor) and etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 15:23
	256	(438/381).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 17:08
	70905	inductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/20 17:09
	76	((438/381).CCLS.) and inductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/21 09:31
	17	((438/381).CCLS.) and inductor and polysilicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/21 09:32
	961	(257/48).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:01
	817207	coil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:01
	15	((257/48).CCLS.) and coil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:03
	1481	lateral adj etch or lateral adj etching	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 08:03

	128	coil and (lateral adj etch or lateral adj etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/02 08:07
	2082394	measure or measured or measuring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/02 08:08
	81	(coil and (lateral adj etch or lateral adj etching)) and (measure or measured or measuring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/02 08:08
	2	("5739909").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/02 08:24
	11	5739909.URPN.	USPAT	2003/06/02 08:22
	3	("4763183" "5114233" "5539766").PN.	USPAT	2003/06/02 08:23
	182	scatterometry	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/02 08:24
	18	coil and scatterometry	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/02 08:37
	844792	monitor or monitoring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/02 08:38
	23	coil and (lateral adj etch or lateral adj etching) and (monitor or monitoring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/02 08:44
	0	6340603.URPN.	USPAT	2003/06/02 08:41
	10	("4522681" "4817815" "5007982" "5242536" "5877032" "5910011" "5926740" "6040248" "6121123" "6141183").PN.	USPAT	2003/06/02 08:41
	0	6340603.URPN.	USPAT	2003/06/02 08:43
	77609	inductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/02 08:45
	5	(lateral adj etch or lateral adj etching) and (monitor or monitoring) and inductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/02 08:46
	1096	(438/14).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/02 08:46
	1	(lateral adj etch or lateral adj etching) and ((438/14).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/02 08:47